

Revision History 512 Kb x16 Pseudo Static RAM 48ball-FPBGA

Revision	Details	Date
Rev 1.0	Preliminary datasheet	Aug. 2018

Alliance Memory Inc. 511 Taylor Way, San Carlos, CA 94070 TEL: (650) 610-6800 FAX: (650) 620-9211 Alliance Memory Inc. reserves the right to change products or specification without notice



GENERAL DESCRIPTION

The AS1C512K16PL-70BIN is 8,388,608 bits of Pseudo SRAM which uses DRAM type memory cells, but this device has refresh-free operation and extreme low power consumption technology. Furthermore the inter-face is compatible to a low power Asynchronous type SRAM. The AS1C512K16PL-70BIN is organized as 524,288 Words x 16 bit.

FEATURES

- Organization :512K x16

- Address access speed 70ns

- Power Supply Voltage: 1.7 ~ 1.95V

- Separated I/O power(VccQ) & Core power(Vcc)

- Three state outputs

- Byte read/write control by UB# / LB#

- Auto-TCSR for power saving

- Package type: 48-FPBGA 6.0x7.0

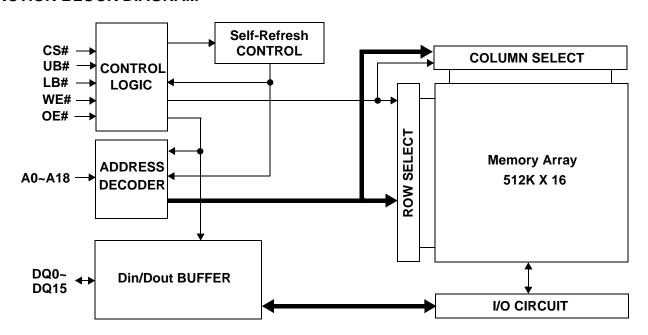
- Operating Temperature

.Industrial (Wireless): -30 $^{\circ}$ C ~ 85 $^{\circ}$ C

PRODUCT FAMILY

				Power Dissipation			
Part Number	Operating Temp.	Power Supply	Speed (t _{RC})	a	Operating I _{CC} (Max.)		
i art isdinisei				Standby (I _{SB} , Max.)	I _{CC1} (f = 1MHz)	I _{CC2} (f = f _{max})	
AS1C512K16PL-70BIN	-30 ℃to 85 ℃	1.7V to 1.95V	70ns	90uA	5mA	25mA	

FUNCTION BLOCK DIAGRAM



PIN DESCRIPTION (48-FPBGA-6.00x7.00)

	1	2	3	4	5	6
Α	LB#	OE#	(A0)	(A1)	A2	NC
В	DQ8	UB#	(A3)	A4	CS#	DQ0
С	DQ9	DQ10	(A5)	(A6)	DQ1	DQ2
D	VSSQ	DQ11	(A17)	(A7)	DQ3	VCC
E	VCCQ	DQ12	DNU	(A16)	DQ4	VSS
F	DQ14	DQ13	(A14)	A15	DQ5	DQ6
G	DQ15	NC	(A12)	(A13)	WE#	DQ7
н	A18	(A8)	(A9)	A10	A11	NC

TOP VIEW (Ball Down)

Name	Function	Name	Function
CS#	Chip select input	LB#	Lower byte (DQ _{0~7})
OE#	Output enable input	UB#	Upper byte (DQ _{8~15})
WE#	Write enable input	VCC	Power supply
DQ ₀₋₁₅	Data in-out	VCCQ	I/O power supply
A ₀₋₁₈	Address inputs	VSS(Q)	Ground
DNU	Do not use	NC	No connection



ABSOLUTE MAXIMUM RATINGS 1)

Parameter	Symbol	Ratings	Unit	
Voltage on Any Pin Relative to Vss	V _{IN} , V _{OUT}	-0.2 to V _{CCQ} +0.3	V	
Voltage on Vcc supply relative to Vss	V_{CC}, V_{CCQ}	-0.2 ²⁾ to 2.5	V	
Power Dissipation	P _D	1.0	W	
Storage Temperature	T _{STG}	-65 to 150	°C	
Operating Temperature	Wireless	T _A	-30 to 85	°C

Stresses greater than those listed above "Absolute Maximum Ratings" may cause permanent damage to the device.
 Functional operation should be restricted to recommended operating condition. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

FUNCTIONAL DESCRIPTION

CS#	OE#	WE#	LB#	UB#	DQ _{0~7}	DQ _{8~15}	Mode	Power
Н	Х	Х	Х	Х	High-Z	High-Z	Deselected	Stand by
L	Н	Н	L	Х	High-Z	High-Z	Output Disabled	Active
L	Н	Н	Х	L	High-Z	High-Z	Output Disabled	Active
L	L	Н	L	Н	Data Out	High-Z	Lower Byte Read	Active
L	L	Н	Н	L	High-Z	Data Out	Upper Byte Read	Active
L	L	Н	L	L	Data Out	Data Out	Word Read	Active
L	Х	L	L	Н	Data In	High-Z	Lower Byte Write	Active
L	Х	L	Н	L	High-Z	Data In	Upper Byte Write	Active
L	Х	L	L	L	Data In	Data In	Word Write	Active

Note:

1. X means don't care. (Must be low or high state)

^{2.} Undershoot at power-off: -1.0V in case of pulse width ≤ 20ns



RECOMMENDED DC OPERATING CONDITIONS

Parameter	Symbol	Min	Тур	Max	Unit
Cupply voltage	V _{CC}	1.7	1.8	1.95	V
Supply voltage	V _{CCQ}	1.7	1.8	1.95	V
Ground	V _{SS} , V _{SSQ}	0	0	0	V
Input high voltage	V _{IH}	V _{CCQ} - 0.4	-	$V_{CCQ} + 0.2^{1)}$	V
Input low voltage	V _{IL}	-0.2 ²⁾	-	0.4	V

- 1. Overshoot: Vcc +1.0 V in case of pulse width ≤ 20ns
- 2. Undershoot: -1.0 V in case of pulse width ≤ 20ns
- 3. Overshoot and undershoot are sampled, not 100% tested.

$\textbf{CAPACITANCE}^{1)} \hspace{0.2cm} (f = 1 MHz, T_A = 25^{o}C)$

Item	Symbol	Test Condition	Min	Max	Unit
Input capacitance	C _{IN}	V _{IN} =0V	-	8	pF
Input/Output capacitance	C _{IO}	V _{IO} =0V	-	8	pF

^{1.} Capacitance is sampled, not 100% tested

DC AND OPERATING CHARACTERISTICS

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Input leakage current	I _{LI}	$V_{IN} = V_{SS}$ to V_{CCQ} , $V_{CC=} V_{CCmax}$	-1	-	1	uA
Output leakage current	I _{LO}	$ \begin{split} & \text{CS\#=V}_{\text{IH}} \text{ , OE\#=V}_{\text{IH}} \text{ or WE\#=V}_{\text{IL}} \text{ ,} \\ & \text{V}_{\text{IO}}\text{=V}_{\text{SS}} \text{ to V}_{\text{CCQ}} \text{ , V}_{\text{CC=}}\text{V}_{\text{CCmax}} \end{split} $	-1	-	1	uA
Average operating current	I _{CC1}	Cycle time = 1us, I_{IO} =0mA, 100% duty, CS# \leq 0.2V, $V_{IN}\leq$ 0.2V or $V_{IN}\geq$ V _{CCQ} -0.2V	-	-	5	mA
	I _{CC2}	Cycle time = Min, I_{IO} =0mA, 100% duty, CS#= V_{IL} , V_{IN} = V_{IL} or V_{IH}	-	-	25	mA
Page access operating current	I _{CCP}	$tPC = Min,CS\#=V_{IL},\ I_{IO}=0mA,\ Page$ add. cycling.	-	-	15	mA
Output low voltage	V _{OL}	$I_{OL} = 0.5 \text{mA}, V_{CC=} V_{CCmin}$	-	-	0.2*V _{CCQ}	V
Output high voltage	V _{OH}	$I_{OH} = -0.5$ mA, $V_{CC} = V_{CCmin}$	0.8*V _{CCQ}	-	-	V
Standby current (CMOS) $I_{SB} = \frac{\text{CS}\#_{\geq}\text{V}_{CCQ}-0.2\text{V}, \text{ Other inputs} = 0 \sim \text{V}_{CCQ}}{(\text{Typ. condition}: \text{V}_{CC}=1.8\text{V} @ 25^{\circ}\text{C})}$ $(\text{Max. condition}: \text{V}_{CC}=1.9\text{V} @ 85^{\circ}\text{C})$		(Typ. condition : V _{CC} =1.8V @ 25°C)	-	-	90	uA

^{1.} Maximum Icc specifications are tested with $V_{CC} = V_{CCmax}$.



AC OPERATING CONDITIONS

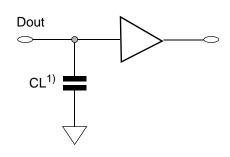
Test Conditions (Test Load and Test Input/Output Reference)

Input Pulse Level : 0.2V to V_{CCQ} -0.2V

Input Rise and Fall Time : 5ns Input and Output reference Voltage : V_{CCQ}/2

Output Load (See right) : $CL^{1)} = 30pF$

1. Including scope and Jig capacitance

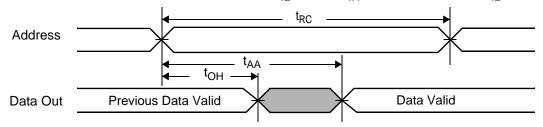


AC CHARACTERISTICS

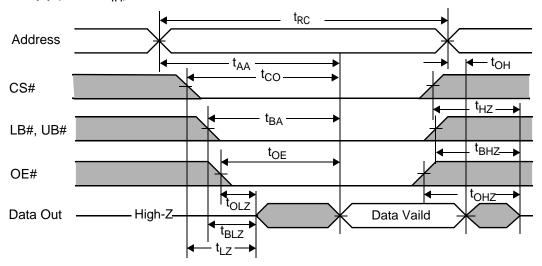
		Symbol	Sp	Speed	
	Parameter List	Symbol	Min	Max	Unit
	Read Cycle Time	t _{RC}	70	10k	ns
	Address access time	t _{AA}	-	70	ns
	Chip enable to data output	t _{CO}	-	70	ns
	Output enable to valid output	t _{OE}	-	25	ns
	UB#, LB# enable to data output	t _{BA}	-	25	ns
Dood	Chip enable to low-Z output	t _{LZ}	10	-	ns
Read	UB#, LB# enable to low-Z output	t _{BLZ}	0	-	ns
	Output enable to low-Z output	t _{OLZ}	0	-	ns
	Chip disable to high-Z output	t _{HZ}	0	20	ns
	UB#, LB# disable to high-Z output	t _{BHZ}	0	20	ns
	Output disable to high-Z output	t _{OHZ}	Symbol t _{RC} 70 t _{AA} - t _{CO} - t _{OE} - t _{BA} - t _{LZ} 10 t _{BLZ} 0 t _{OLZ} 0 t _{HZ} 0 t _{BHZ} 0	20	ns
	Output hold from Address change	t _{OH}	5	Max 10k 70 70 25 25 20 20	ns
	Write Cycle Time	t _{WC}	70	- 20 20 20 - 10k 	ns
	Chip enable to end of write	t _{CW}	60	-	ns
	Address setup time	t _{AS}	0	-	ns
	Address valid to end of write	t _{AW}	60	-	ns
	UB#, LB# valid to end of write	t _{BW}	60	-	ns
Write	Write pulse width	t _{WP}	50	-	ns
	Write recovery time	t _{WR}	0	-	ns
	Write to output high-Z	t _{WHZ}	0	20	ns
	Data to write time overlap	t _{DW}	20	-	ns
	Data hold from write time	t _{DH}	0	-	ns
	End write to output low-Z	t _{OW}	5	-	ns
	Maximum cycle time	t MRC*1)	-	10k	ns
Page	Page mode cycle time	t _{PC} *1)	25	-	ns
	Page mode address access time		-	25	ns

TIMING DIAGRAMS

READ CYCLE (1) (Address controlled, CS#=OE#= V_{IL} , WE#= V_{IH} , UB# or/and LB#= V_{IL})



READ CYCLE (2) (WE#=V_{IH})

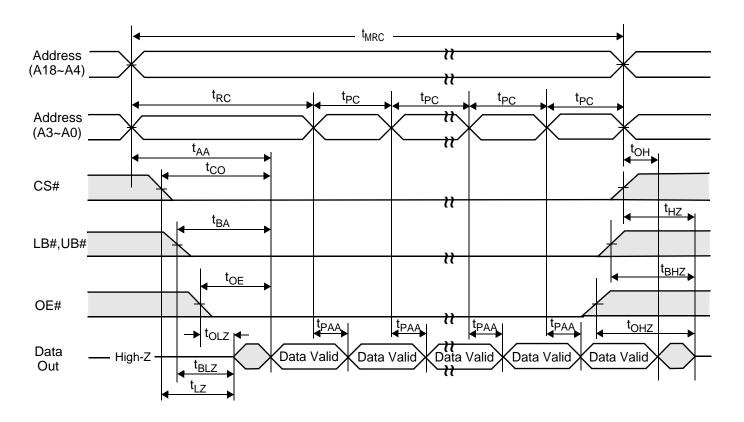


NOTES (READ CYCLE)

- 1. t_{HZ} , t_{BHZ} and t_{OHZ} are defined as the time at which the outputs achieve the open circuit conditions and are not referenced to output voltage levels.
- 2. Do not Access device with cycle timing shorter than t_{RC} for continuous periods > 10us.

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PAGE READ CYCLE (2) (WE#=V_{IH}, 16 Words access)

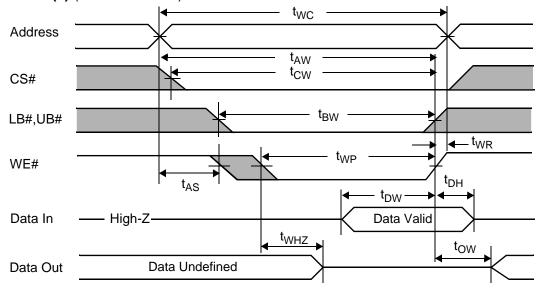


NOTES (READ CYCLE)

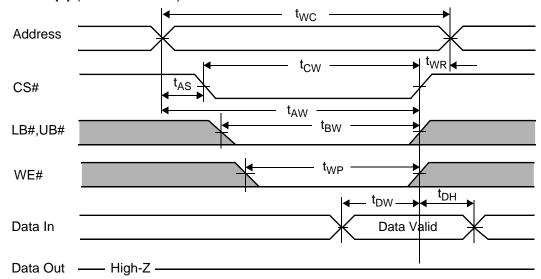
- 1. t_{HZ} , t_{BHZ} and t_{OHZ} are defined as the time at which the outputs achieve the open circuit conditions and are not referenced to output voltage levels.
- 2. Do not Access device with cycle timing shorter than t_{RC} for continuous periods > 10us.



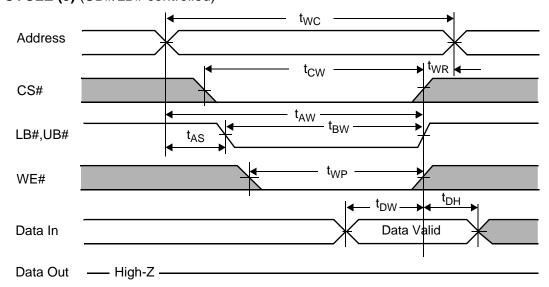
WRITE CYCLE (1) (WE# controlled)



WRITE CYCLE (2) (CS# controlled)



WRITE CYCLE (3) (UB#/LB# controlled)





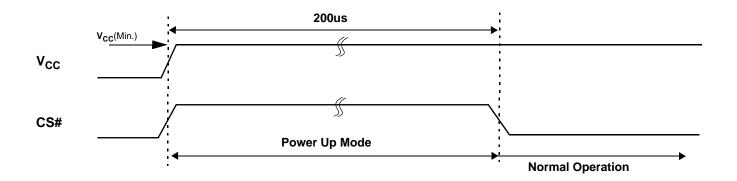
NOTES (WRITE CYCLE)

- 1. A write occurs during the overlap(t_{WP}) of low CS#, low WE# and low UB# or LB#. A write begins at the last transition among low CS# and low WE# with asserting UB# or LB# low for single byte operation or simultaneously asserting UB# and LB# low for word operation. A write ends at the earliest transition among high CS# and high WE#. The t_{WP} is measured from the beginning of write to the end of write.
- 2. t_{CW} is measured from CS# going low to end of write.
- 3. $t_{\mbox{\scriptsize AS}}$ is measured from the address valid to the beginning of write.
- 4. t_{WR} is measured from the end of write to the address change. t_{WR} applied in case a write ends as CS# or WE# going high.
- 5. Do not access device with cycle timing shorter than t_{WC} for continuous periods > 10us.

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TIMING WAVEFORM OF POWER UP



NOTE (POWER UP)

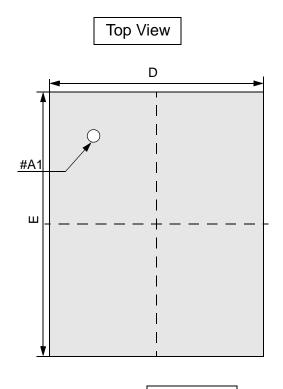
1. After Vcc reaches Vcc(Min.), wait 200us with CS# high. Then you get into the normal operation.

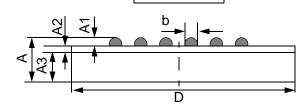
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Unit: millimeters

PACKAGE DIMENSION

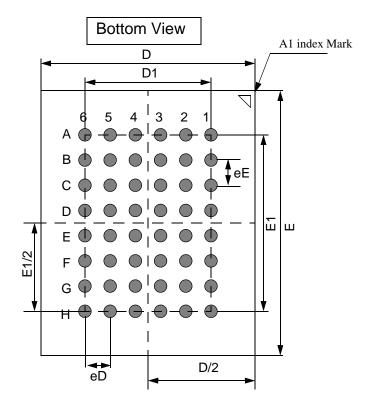
48 Ball Fine Pitch BGA (0.75mm ball pitch)

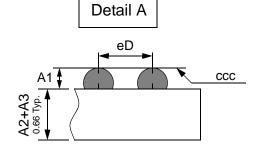




Side View

	Min	Тур	Max
Α	-	-	1.00
A1	0.22	-	0.32
A2	-	0.21	-
А3	-	0.45	-
b	0.32	-	0.42
D	5.90	6.00	6.10
Е	6.90	7.00	7.10
D1	-	3.75	-
E1	-	5.25	-
еE	-	0.75	-
eD	-	0.75	-
ccc	-	-	0.08





NOTES.

1. Bump counts : 48(8row x 6column)

2. Bump pitch : (x,y)=(0.75x0.75) (typ.)

3. All tolerance are +/-0.050 unless otherwise specified.

4. Typ: Typical

5. ccc is coplanarity: 0.08(Max)



PART NUMBERING SYSTEM

AS1C	512K16PL	-70	В	I	N	XX
PSEUDO SRAM	512K16=512kb x 16 PL=Low Power PSEUDO SRAM	70ns	B = FBGA	I=Industrial (-30° C~+85° C)	Indicates Pb and Halogen Free	Packing Type None:Tray TR:Reel



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